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## CURRICULUM VITAE

### PERSONAL INFORMATION

**Name** LORENZI, Paolo  
**Address**  
**Telephone**  
**E-mail**  
**Nationality** Italian  
**Date of birth** FEBRUARY 7, 1982

### WORK EXPERIENCE

- March 2011 – Until now (2013) **“Research Collaborator”** (*Assegnista di Ricerca*) at the Dipartimento di Ingegneria Elettronica - “La Sapienza” University of Rome to perform **“Nanoelectronic memories”**.  
The subject of the work focused on electrical characterization and modeling of resistive memory cells.
- October 2009 – January 2011 **“Ph.D. Student”** at the CEA/LETI/MINATEC of Grenoble, France, in collaboration with the Institut National Polytechnique de Grenoble (INPG) to perform **“Resistive memory cells for intelligent circuit application.”**  
The subject of the work focused on the electrical characterization of dielectric, semiconductor and metal films for application in CMOS microelectronics.
- February 2009 - May 2009 **“Research Collaborator”** at the Dipartimento di Ingegneria Elettronica - “La Sapienza” University of Rome to perform **“Workbench setup for the automation of data retention measurements in TANOS flash memories.”**  
The work focused on the electrical characterization, analysis and modelling of semiconductor memories.
- October 2008 – January 2009 Engaged as **“Research Collaborator”** at the Dipartimento di Ingegneria Elettronica - “La Sapienza” University of Rome to perform **“Pulse programming algorithms for new generations NAND memory cells.”**  
The project focused on the electrical characterization of high-k dielectrics for memories applications.
- September 2005 – August 2006 Collaborator at library of Dipartimento di Fisica Tecnica – “La Sapienza” University of Rome
- September 2002 – August 2004 Collaborator at admission office of Corso di laurea Ingegneria Elettronica – “Roma Tre” University of Rome

### PUBLICATIONS

- 2013 **“Impact of the forming conditions and electrode metals on read disturb in HfO<sub>2</sub>-based RRAM”**, *P. Lorenzi, P; R. Rao; F. Irrera; Microelectronics Reliability, 2013, in press*
- January 2013 **“Forming Kinetics in HfO<sub>2</sub> - Based RRAM Cells”**, *P. Lorenzi, P; R. Rao; F. Irrera; Electron Devices, IEEE Transactions on , vol.60, no.1, pp.438-443, Jan. 2013*
- May 2012 (Milan, IT) **“Impact of Forming Pulse Geometry and Area Scaling on Forming Kinetics and Stability of the Low Resistance State in HfO<sub>2</sub>-Based RRAM Cells,”** *P. Lorenzi; R. Rao; F. Irrera, International Memory Workshop IMW 2012*

- December 2011 (USA) **“Experimental and Theoretical Study of Electrode Effects in HfO<sub>2</sub> based RRAM”**, C. Cagli, J. Buckley, V. Jousseume, T. Cabout, A. Salaun, H. Grampeix, J. F. Nodin, H. Feldis, A. Persico, J. Cluzel, P. Lorenzi, L. Massari, R. Rao, F. Irrera, F. Aussenac, C. Carabasse, M. Coue, P. Calka, E. Martinez, L. Perniola, P. Blaise, Z. Fang, Y. H. Yu, G. Ghibaudo, D. Deleruyelle, M. Bocquet, C. Müller, A. Padovani, O. Pirrotta, L. Vandelli, L. Larcher, G. Reimbold, B. de Salvo; IEDM 2011
- April 2011 **“Comparative study of non-polar switching behaviors of NiO- and HfO<sub>2</sub>-based oxide resistive-RAMs”** V. Jousseume, A. Fantini, J.F. Nodin, C. Guedj, A. Persico, J. Buckley, S. Tirano, P. Lorenzi, R. Vignon, H. Feldis, S. Minoret, H. Grampeix, A. Roule, S. Favier, E. Martinez, P. Calka, N. Rochat, G. Auvert, J.P. Barnes, P. Gonon, C. Vallée, L. Perniola, B. De Salvo, *Solid-State Electronics*, Volume 58, Issue 1, April 2011, Pages 62-67
- December 2010 (San Diego, USA) **“A study of the HRS and LRS temperature behavior of Pt/HfO<sub>2</sub>/Pt based Oxide Resistive RAM”**, Lorenzi P., Singh P., Buckley J., Jousseume V., Nodin J-F., Grampeix H., Persico A., Betti Beneventi G., Tirano S., Perniola L., De Salvo B.; SISC 2010
- May 2010 (Seul, Korea) **“Comparative study of non-polar switching behaviors of NiO- and HfO<sub>2</sub>-based Oxide Resistive-RAMs”**, Jousseume, V.; Fantini, A.; Nodin, J.F.; Guedj, C.; Persico, A.; Buckley, J.; Tirano, S.; Lorenzi, P.; Vignon, R.; Feldis, H.; Minoret, S.; Grampeix, H.; Roule, A.; Favier, S.; Martinez, E.; Calka, P.; Rochat, N.; Auvert, G.; Barnes, J.P.; Gonon, P.; Vallee, C.; Perniola, L.; De Salvo, B.; *Memory Workshop (IMW)*, 2010 IEEE International
- March 2010 (Glasgow, UK) **“Advanced Characterization of Metal/High-k Interface”**, F. Irrera, P. Lorenzi, R. Rao, R. Simoncini, G. Ghidini, H.D.B. Gottlob, M. Schmidt; ULIS 2010
- March 2010 **“Electron-Related Phenomena at the TaN/Al<sub>2</sub>O<sub>3</sub> Interface”**, Rao, R.; Lorenzi, P.; Ghidini, G.; Palma, F.; Irrera, F., *Electron Devices*, IEEE Transactions on, Volume: 57, Issue: 3, 2010
- July 2009 (Genova, IT) **“Charge trapping NanoElectronic memory”**, Lorenzi, P. Rao, R. Palma, F. Irrera, F. Ghidini, G. Dipt. di Ing. Elettron., Univ. La Sapienza, Rome, Italy, Nanotechnology, 2009. IEEE-NANO 2009. 9th IEEE Conference on
- October 2009 **“Charge Trapping Non Volatile Memory”**, Paolo Lorenzi, Rosario Rao, Gabriella Ghidini, Fabrizio Palma, and Fernanda Irrera, *ECS Transactions*. 25 (7), 269 (2009)
- January 2006 **“Programmable analog circuits yield single-chip sinusoidal oscillators”**, S. Salvatori, P. Lorenzi, *EDN: Information, News, & Business Strategy for Electronics Design Engineers*, 19/1/2006, <http://www.edn.com/contents/images/6298269.pdf>

## EDUCATION AND TRAINING

- July 2008 **Master's Degree in Electronic Engineering** at “La Sapienza” University of Rome.  
Mark: **110/110 cum laude**  
**Thesis:** “Analysis and characterization of Flash memories with high-k IPD.”
- December 2004 **Bachelor's Degree in Electronic Engineering** at “Roma Tre” University of Rome.  
Mark: **110/110 cum laude**  
**Thesis:** “Analysis and characterization of programmable analog devices”.
- July 2001 **High School Degree** at “Antonio Labriola” Liceo Scientifico Statale of Rome.  
Mark: **100/100**

## PERSONAL SKILLS AND COMPETENCES

MOTHER TONGUE      ITALIAN

## OTHER LANGUAGES

**ENGLISH**  
Excellent  
Good  
Excellent

- Reading skills
- Writing skills
- Verbal skills

**FRENCH**  
Excellent  
Good  
Excellent

- Reading skills
- Writing skills
- Verbal skills

## TECHNICAL SKILLS AND COMPETENCES

**Clean Room:** continual permanence in a **100/10 class clean room** at CEA/LETI (Grenoble) of 8.000m<sup>2</sup> of surface **following the technology process flow** of microelectronic wafer lots.

**Microscopy:** performing **SEM (Scanning Electron Microscopy) in-line observations on MEB 5000 and MEB 4160** on entire or cut wafers to observe depositions thicknesses, material adhesion and check the results of particular processes steps.

**Electrical characterization:** knowledge of the laboratory electrical measurements techniques for steady-state and transient characterization of semiconductor electronic devices. In particular, matured skills in performing: **current-voltage, current-time, current-temperature** measurements; **pulsed C-V** for monitoring trapping and detrapping transients in defected oxides and semiconductors; **solid-state device modeling** finite element TCAD; **characterization and modeling of conduction mechanism** in oxides and semiconductors. Matured skills in the usage of the principal characterization laboratory equipments: **electrometers, LCR meters, pulses generators, oscilloscopes, semiconductor parameter analyzers**.

Knowledge of automation and simulation software **Labview**

Knowledge of numerical analysis tools **Matlab** and **Mathcad**

Knowledge of programming and hardware description languages: **Java, C, HTML, VHDL, Assembler**.

Knowledge of circuit simulation software: **Orcad Spice, NgSpice**.

Knowledge of operating systems and principal office software: **Microsoft Windows, Linux, Microsoft Word, Power Point, Excel, KaleidaGraph, Origin**.

## ORGANIZATIONAL SKILLS AND COMPETENCES

Team work and coordination of activities driven by problem solving issues. Capability to work with heterogeneous kind of professionals in order to reach common targets.

## DRIVING LICENCE(S)

European Car (B).